

IFW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : PAN et al. Confirmation No: 4127
Appl. No. : 10/617,679
Filed : July 14, 2003
Title : METHOD OF POLISHING SEMICONDUCTOR COPPER
INTERCONNECT INTEGRATED WITH EXTREMELY LOW
DIELECTRIC CONSTANT MATERIAL

TC/A.U. : 3723
Examiner : H. Shakeri

Docket No.: : PANW3002/REF
Customer No: : 23364

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of August 23, 2004, in connection with the above-identified application. This response is timely filed.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.